

MAYS062

Silicon planar type

For waveform clipper

For surge absorption circuits

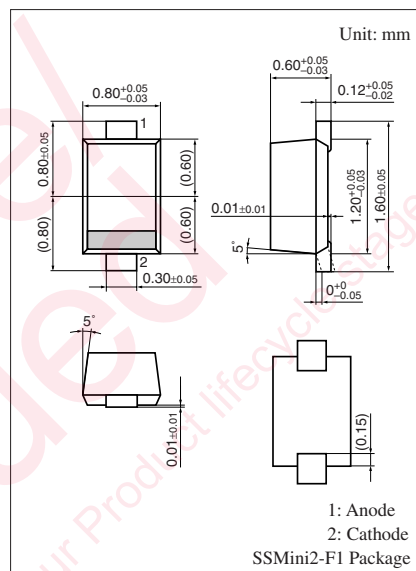
■ Features

- Low joint capacity zener diode

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Repetitive peak forward current	I_{FRM}	200	mA
Total power dissipation *	P_{tot}	150	mW
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

Note) *: $P_{tot} = 150$ mW achieved with a printed circuit board



Marking Symbol: E6

■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$ *1

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 10$ mA		0.9	1.0	V
Zener voltage *2	V_Z	$I_Z = 5$ mA	5.9		6.5	V
Reverse current	I_R	$V_R = 5.5$ V			3	μA
Zener rise operating resistance	R_{ZK}	$I_Z = 0.5$ mA			100	Ω
Zener operating resistance	R_Z	$I_Z = 5$ mA			30	Ω
Terminal capacitance	C_t	$V_R = 0$ V, $f = 1$ MHz		8		pF

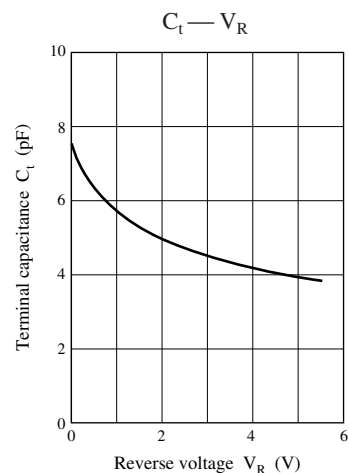
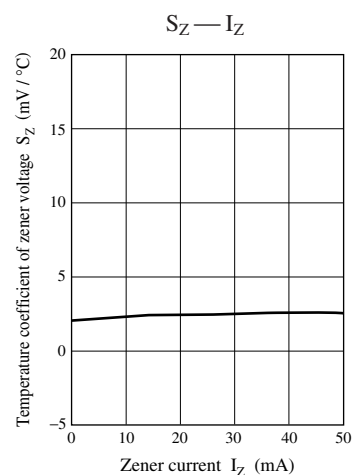
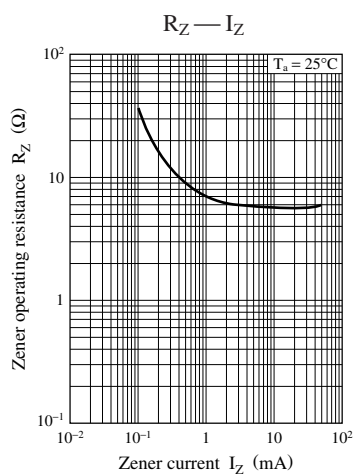
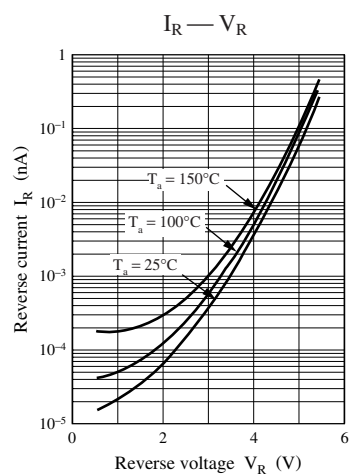
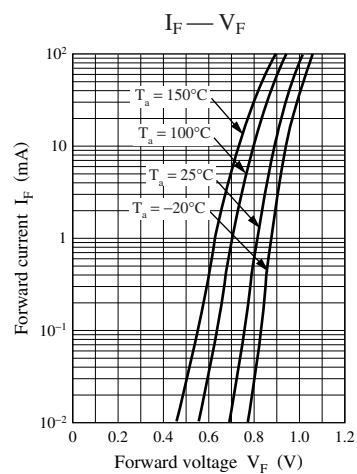
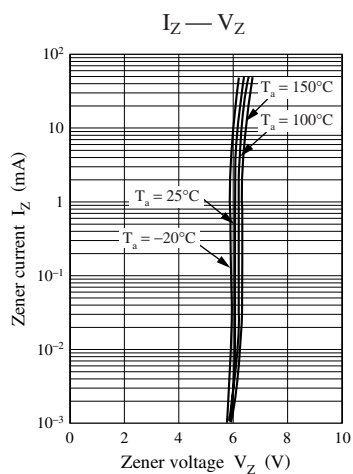
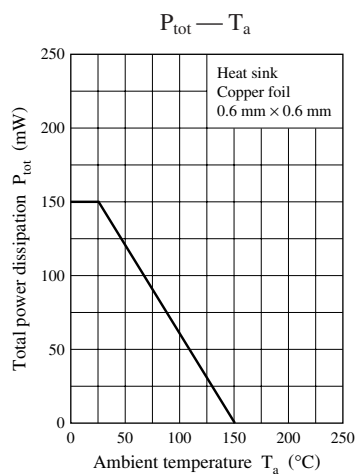
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Absolute frequency of input and output is 5 MHz.

3. *1: The temperature must be controlled 25°C for V_Z measurement.

V_Z value measured at other temperature must be adjusted to V_Z (25°C).

*2: V_Z guaranteed 20 ms after current flow.



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